版本	修订日期	有修订的页码	修订涉及的内容	拟制	审核
A	202				

ching;Low Thermal

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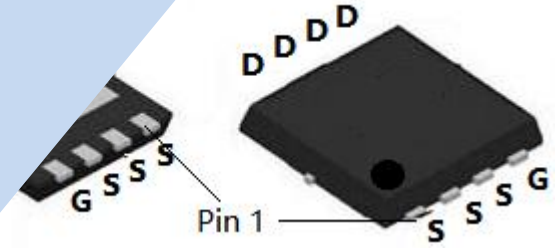
chronous Buck Conventer for
,Load Switch.



、2、3： S PIN4：G PIN5、6、7、8：D

/ Marking

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See Marking Instructions.

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Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	100	V
Drain Current - Continuous	I_D	168	A
Drain Current – Pulsed	I_{DM}	400	A
Gate-Source Voltage	V_{GS}	±20	V
Power Dissipation	$P_D(T_c=25℃)$	215	W
Single Pulse Avalanche Energy(L=0.5mH)	E_{AS}	563	mJ
Avalanche Current(L=0.5mH)	I_{AS}	37.5	A
Junction and Storage Temperature Range	T_j, T_{stg}	-55 to 150	℃
Thermal resistance, junction - ambient t ≤ 10s	$R_{\theta JA}$		

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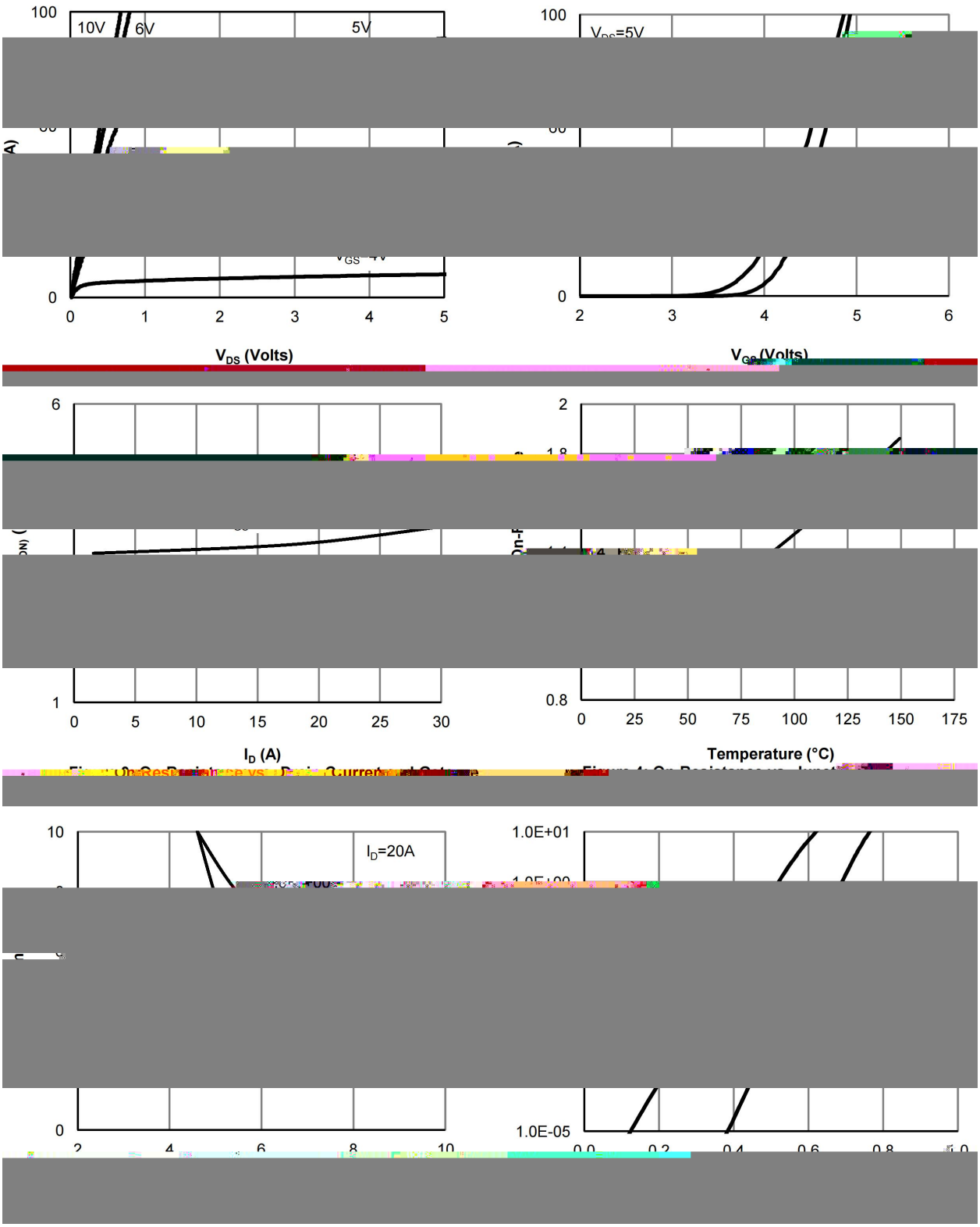
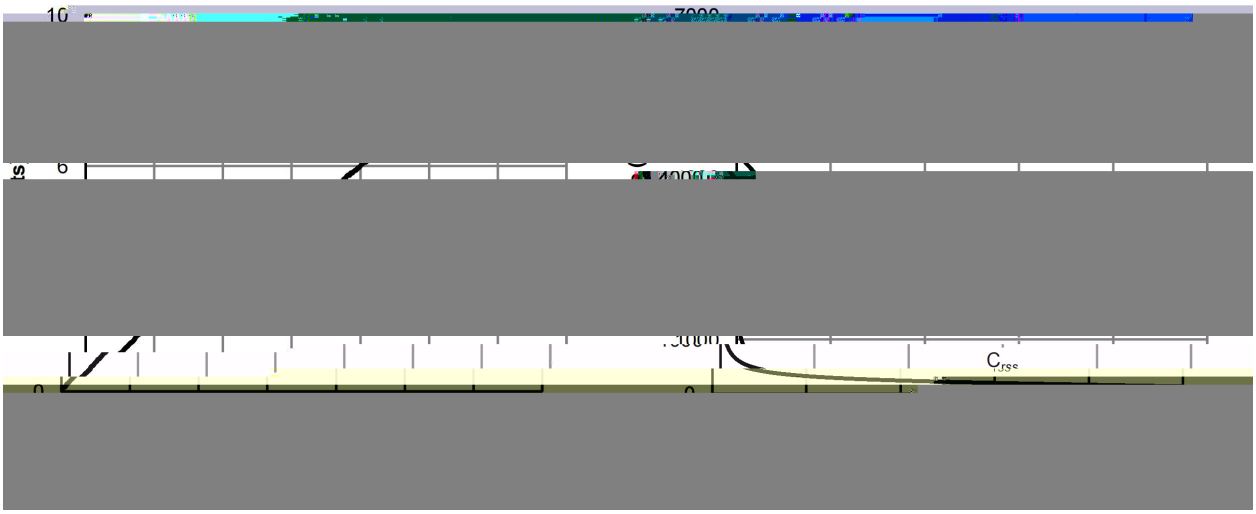
/ Electrical Characteristics(Ta=25)

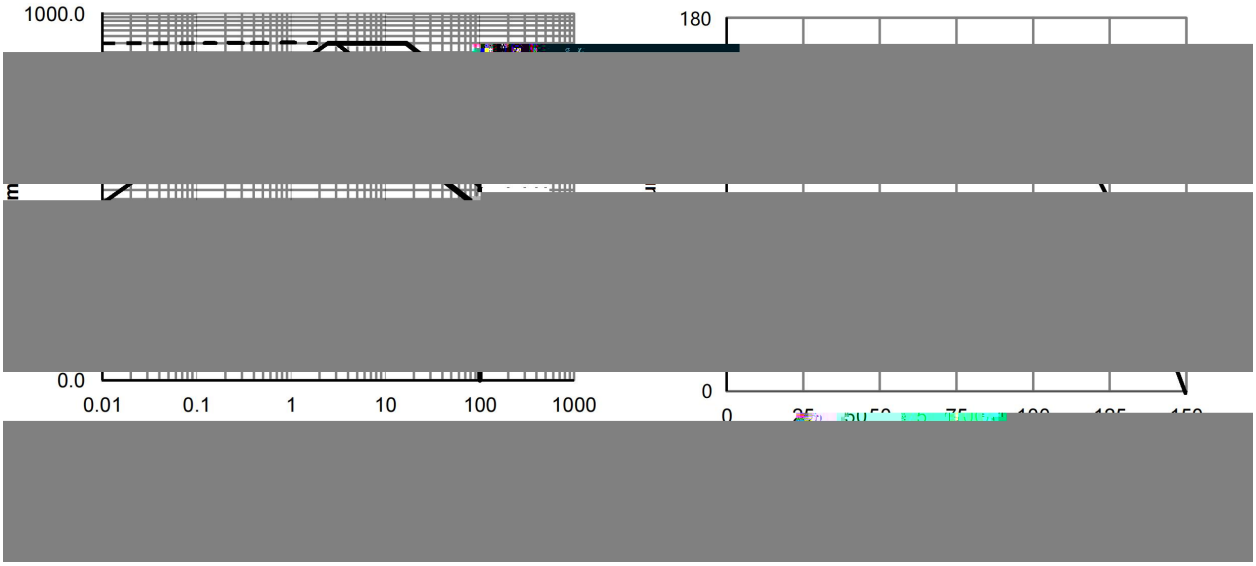
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=10V V_{DS}=50V R_L=2.5 Ω R_{GEN}=3 Ω		19		ns
Turn-On Rise Time	t_r			8		
Turn-Off Delay Time	$t_{d(off)}$			32		
Turn-Off Fall Time	t_f			11		

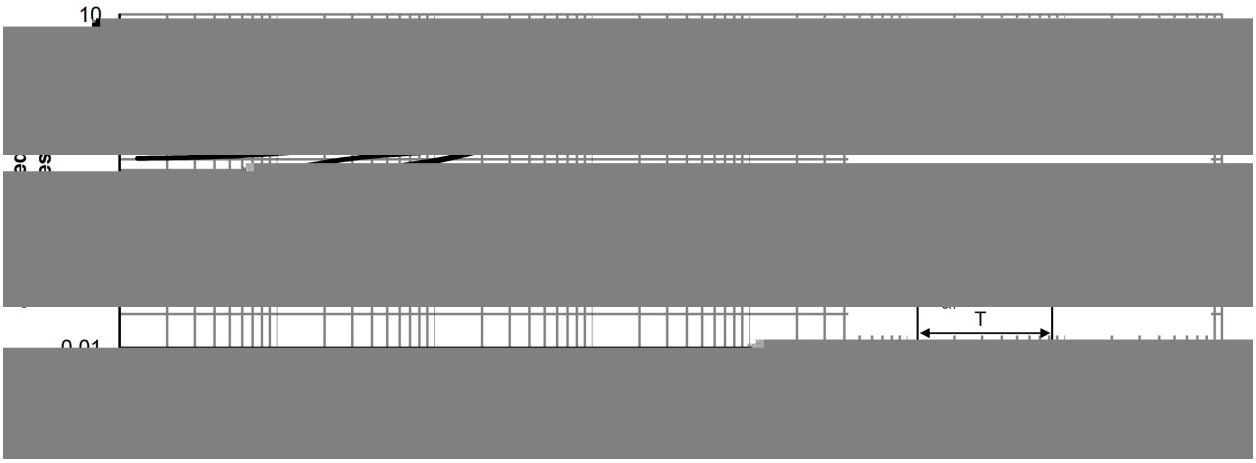
/ Electrical Characteristic Curve



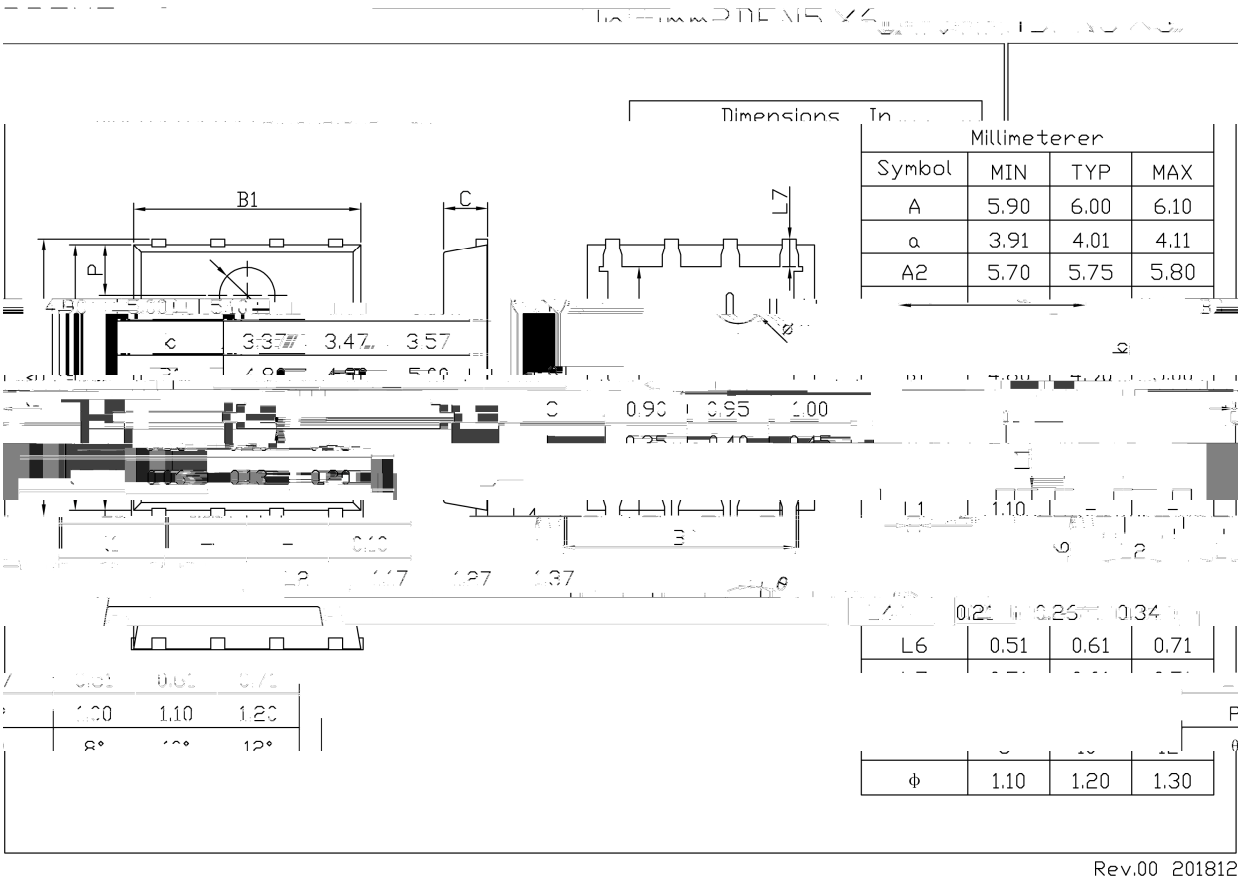
/ Electrical Characteristic Curve





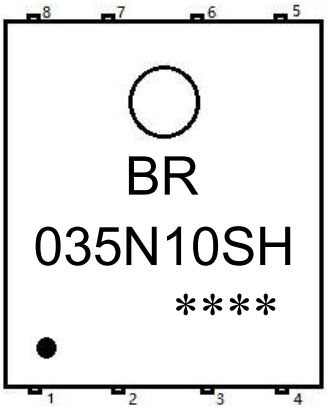


/ Package Dimensions



Symbol	MIN	TYP	MAX
A	5.90	6.00	6.10
a	3.91	4.01	4.11
A2	5.70	5.75	5.80

/ Marking Instructions



BR

035N10SH

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Note

BR	Company Code
035N10SH	Product Type
****:	Lot No. Code, code change with Lot No

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

					Note:
1	150	180	60	90sec;	1.Preheating:150~180℃, Time:60~90sec.
2	245±5			5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3			2	10℃/sec.	3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

260±5℃	10±1 sec.	Temp.:260±5℃	Time:10±1 sec

/ Packaging SPEC.